# XP06115 (XP6115)

### Silicon PNP epitaxial planer transistor

#### For switching/digital circuits

#### Features

- Two elements incorporated into one package. (Transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half.

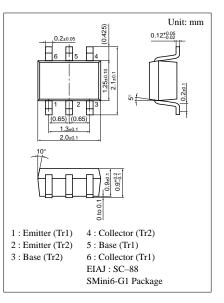
#### Basic Part Number of Element

• UNR1115(UN1115)  $\times$  2 elements

Parameter		Symbol	Ratings	Unit
Rating of element	Collector to base voltage	V <sub>CBO</sub>	-50	V
	Collector to emitter voltage	V <sub>CEO</sub>	-50	V
	Collector current	I <sub>C</sub>	-100	mA
Overall	Total power dissipation	P <sub>T</sub>	150	mW
	Junction temperature	Tj	150	°C
	Storage temperature	T <sub>stg</sub>	-55 to +150	°C

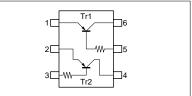
#### Absolute Maximum Ratings (Ta=25°C)

Electrical Characteristics (Ta=25°C)



#### Marking Symbol: 6X

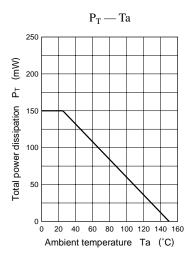
#### Internal Connection

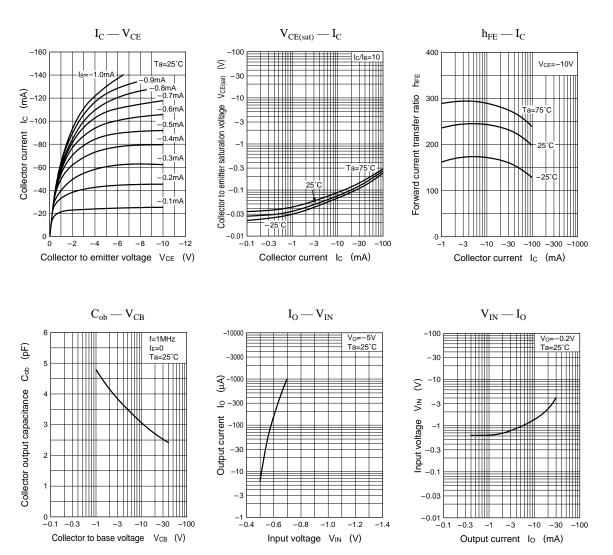


#### Parameter Symbol Conditions Unit min typ max Collector to base voltage V<sub>CBO</sub> $I_C = -10 \mu A$ , $I_E = 0$ -50 V V<sub>CEO</sub> $I_{C} = -2mA, I_{B} = 0$ -50V Collector to emitter voltage $V_{CB} = -50V, I_E = 0$ -0.1μA I<sub>CBO</sub> Collector cutoff current $V_{CE} = -50V, I_B = 0$ -0.5μΑ I<sub>CEO</sub> Emitter cutoff current $I_{EBO}$ $V_{EB} = -6V, I_C = 0$ -0.01mA Forward current transfer ratio $V_{CE} = -10V, I_C = -5mA$ 160 460 h<sub>FE</sub> $V_{CE} = -10V, I_C = -5mA$ 0.99 hFE (small/large)\*1 0.5 Forward current transfer h<sub>FE</sub> ratio Collector to emitter saturation voltage $I_{C} = -10mA$ , $I_{B} = -0.3mA$ -0.25V V<sub>CE(sat)</sub> $V_{CC} = -5V, V_B = -0.5V, R_L = 1k\Omega$ Output voltage high level -4.9 V V<sub>OH</sub> $V_{CC} = -5V, V_B = -2.5V, R_L = 1k\Omega$ V Output voltage low level VOL -0.2Transition frequency $\mathbf{f}_{\mathrm{T}}$ $V_{CB} = -10V$ , $I_E = 1mA$ , f = 200MHz80 MHz Input resistance $R_1$ -30% 10 +30%kΩ

\*1 Ratio between 2 elements

Note) The Part number in the Parenthesis shows conventional part number.





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